

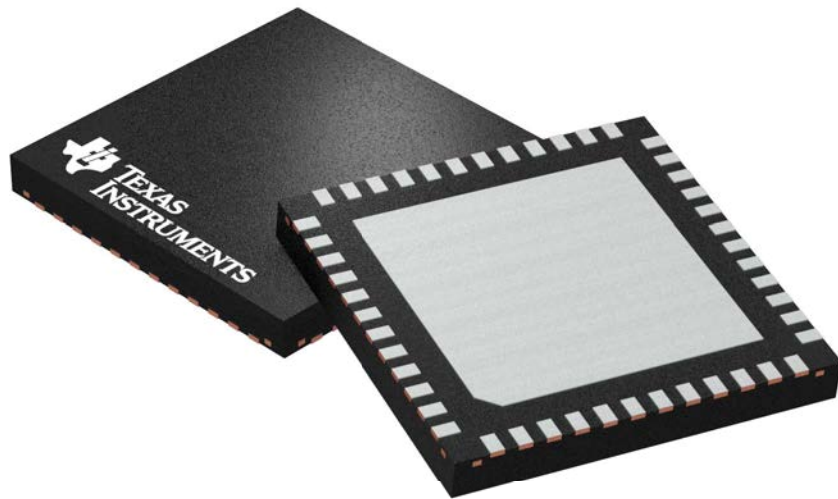
## GENERIC PACKAGE VIEW

**RHS 48**

**WQFN - 0.8 mm max height**

7 x 7 mm, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4205855/C

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